

# HEF4001B-Q100

## Quad 2-input NOR gate

Rev. 1 — 20 February 2013

Product data sheet

### 1. General description

The HEF4001B-Q100 is a quad 2-input NOR gate. The outputs are fully buffered for the highest noise immunity and pattern insensitivity to output impedance.

It operates over a recommended  $V_{DD}$  power supply range of 3 V to 15 V referenced to  $V_{SS}$  (usually ground). Unused inputs must be connected to  $V_{DD}$ ,  $V_{SS}$ , or another input.

This product has been qualified to the Automotive Electronics Council (AEC) standard Q100 (Grade 1) and is suitable for use in automotive applications.

### 2. Features and benefits

- Automotive product qualification in accordance with AEC-Q100 (Grade 1)
  - ◆ Specified from  $-40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$  and from  $-40\text{ }^{\circ}\text{C}$  to  $+125\text{ }^{\circ}\text{C}$
- Fully static operation
- 5 V, 10 V, and 15 V parametric ratings
- Standardized symmetrical output characteristics
- ESD protection:
  - ◆ MIL-STD-883, method 3015 exceeds 2000 V
  - ◆ HBM JESD22-A114F exceeds 2000 V
  - ◆ MM JESD22-A115-A exceeds 200 V ( $C = 200\text{ pF}$ ,  $R = 0\text{ }\Omega$ )
- Complies with JEDEC standard JESD 13-B
- Inputs and outputs are protected against electrostatic effects

### 3. Ordering information

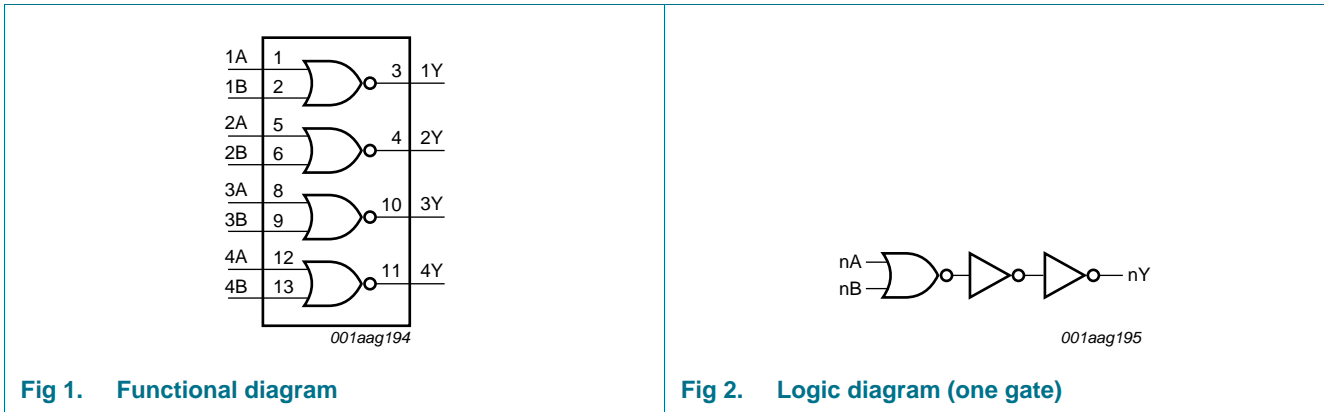
**Table 1. Ordering information**

All types operate from  $-40\text{ }^{\circ}\text{C}$  to  $+125\text{ }^{\circ}\text{C}$

Type number	Package		Version
	Name	Description	
HEF4001BT-Q100	SO14	plastic small outline package; 14 leads; body width 3.9 mm	SOT108-1

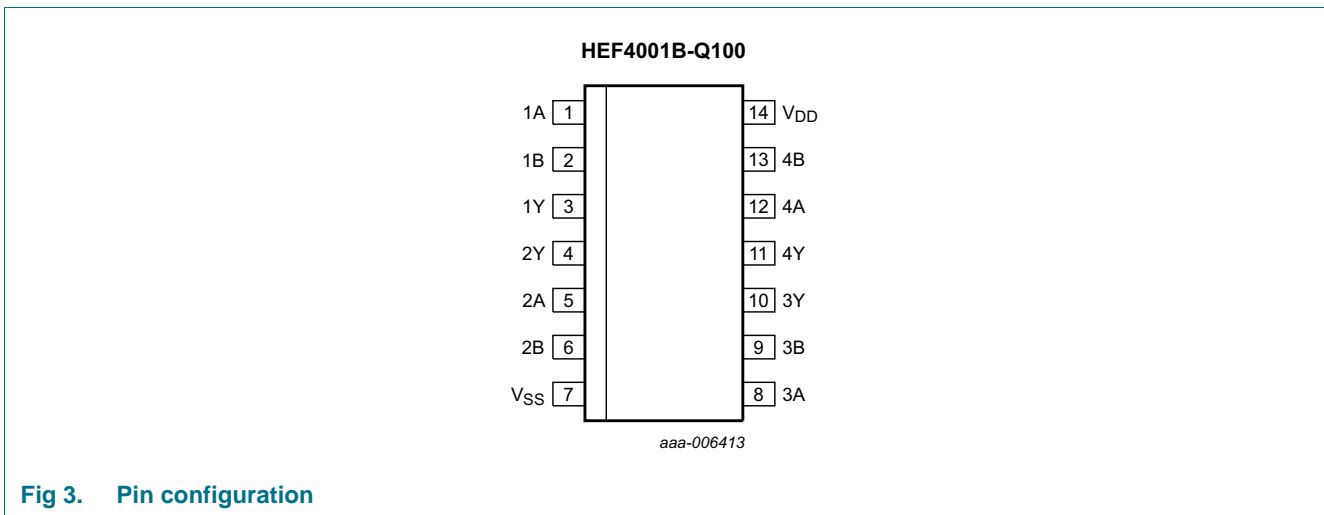


### 4. Functional diagram



### 5. Pinning information

#### 5.1 Pinning



#### 5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
nA	1, 5, 8, 12	input
nB	2, 6, 9, 13	input
nY	3, 4, 10, 11	output
V <sub>SS</sub>	7	ground (0 V)
V <sub>DD</sub>	14	supply voltage

## 6. Functional description

Table 3. Function table<sup>[1]</sup>

Input		Output
nA	nB	nY
L	L	H
L	H	L
H	L	L
H	H	L

[1] H = HIGH voltage level; L = LOW voltage level.

## 7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to  $V_{SS} = 0$  V (ground).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{DD}$	supply voltage		-0.5	+18	V
$I_{IK}$	input clamping current	$V_I < -0.5$ V or $V_I > V_{DD} + 0.5$ V	-	$\pm 10$	mA
$V_I$	input voltage		-0.5	$V_{DD} + 0.5$	V
$I_{OK}$	output clamping current	$V_O < -0.5$ V or $V_O > V_{DD} + 0.5$ V	-	$\pm 10$	mA
$I_{I/O}$	input/output current		-	$\pm 10$	mA
$I_{DD}$	supply current		-	50	mA
$T_{stg}$	storage temperature		-65	+150	°C
$T_{amb}$	ambient temperature		-40	+125	°C
$P_{tot}$	total power dissipation	$T_{amb} = -40$ °C to + 125 °C	<sup>[1]</sup> -	500	mW
P	power dissipation	per output	-	100	mW

[1] For SO14 packages: above  $T_{amb} = 70$  °C,  $P_{tot}$  derates linearly with 8 mW/K.

## 8. Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{DD}$	supply voltage		3	-	15	V
$V_I$	input voltage		0	-	$V_{DD}$	V
$T_{amb}$	ambient temperature	in free air	-40	-	+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{DD} = 5$ V	-	-	3.75	$\mu$ s/V
		$V_{DD} = 10$ V	-	-	0.5	$\mu$ s/V
		$V_{DD} = 15$ V	-	-	0.08	$\mu$ s/V

## 9. Static characteristics

**Table 6. Static characteristics**
 $V_{SS} = 0\text{ V}$ ;  $V_I = V_{SS}$  or  $V_{DD}$ ; unless otherwise specified.

Symbol	Parameter	Conditions	$V_{DD}$	$T_{amb} = -40\text{ }^{\circ}\text{C}$		$T_{amb} = +25\text{ }^{\circ}\text{C}$		$T_{amb} = +85\text{ }^{\circ}\text{C}$		$T_{amb} = +125\text{ }^{\circ}\text{C}$		Unit
				Min	Max	Min	Max	Min	Max	Min	Max	
$V_{IH}$	HIGH-level input voltage	$ I_O  < 1\text{ }\mu\text{A}$	5 V	3.5	-	3.5	-	3.5	-	3.5	-	V
			10 V	7.0	-	7.0	-	7.0	-	7.0	-	V
			15 V	11.0	-	11.0	-	11.0	-	11.0	-	V
$V_{IL}$	LOW-level input voltage	$ I_O  < 1\text{ }\mu\text{A}$	5 V	-	1.5	-	1.5	-	1.5	-	1.5	V
			10 V	-	3.0	-	3.0	-	3.0	-	3.0	V
			15 V	-	4.0	-	4.0	-	4.0	-	4.0	V
$V_{OH}$	HIGH-level output voltage	$ I_O  < 1\text{ }\mu\text{A}$	5 V	4.95	-	4.95	-	4.95	-	4.95	-	V
			10 V	9.95	-	9.95	-	9.95	-	9.95	-	V
			15 V	14.95	-	14.95	-	14.95	-	14.95	-	V
$V_{OL}$	LOW-level output voltage	$ I_O  < 1\text{ }\mu\text{A}$	5 V	-	0.05	-	0.05	-	0.05	-	0.05	V
			10 V	-	0.05	-	0.05	-	0.05	-	0.05	V
			15 V	-	0.05	-	0.05	-	0.05	-	0.05	V
$I_{OH}$	HIGH-level output current	$V_O = 2.5\text{ V}$	5 V	-	-1.7	-	-1.4	-	-1.1	-	-1.1	mA
		$V_O = 4.6\text{ V}$	5 V	-	-0.64	-	-0.5	-	-0.36	-	-0.36	mA
		$V_O = 9.5\text{ V}$	10 V	-	-1.6	-	-1.3	-	-0.9	-	-0.9	mA
		$V_O = 13.5\text{ V}$	15 V	-	-4.2	-	-3.4	-	-2.4	-	-2.4	mA
$I_{OL}$	LOW-level output current	$V_O = 0.4\text{ V}$	5 V	0.64	-	0.5	-	0.36	-	0.36	-	mA
		$V_O = 0.5\text{ V}$	10 V	1.6	-	1.3	-	0.9	-	0.9	-	mA
		$V_O = 1.5\text{ V}$	15 V	4.2	-	3.4	-	2.4	-	2.4	-	mA
$I_I$	input leakage current		15 V	-	$\pm 0.1$	-	$\pm 0.1$	-	$\pm 1.0$	-	$\pm 1.0$	$\mu\text{A}$
$I_{DD}$	supply current	all valid input combinations; $I_O = 0\text{ A}$	5 V	-	0.25	-	0.25	-	7.5	-	7.5	$\mu\text{A}$
			10 V	-	0.5	-	0.5	-	15.0	-	15.0	$\mu\text{A}$
			15 V	-	1.0	-	1.0	-	30.0	-	30.0	$\mu\text{A}$
$C_I$	input capacitance			-	-	-	7.5	-	-	-	pF	

## 10. Dynamic characteristics

**Table 7. Dynamic characteristics**

$T_{amb} = 25\text{ }^{\circ}\text{C}$ ; for waveforms see [Figure 4](#); for test circuit see [Figure 5](#); unless otherwise specified.

Symbol	Parameter	Extrapolation formula <sup>[1]</sup>	V <sub>DD</sub>	Min	Typ	Max	Unit
t <sub>PHL</sub>	HIGH to LOW propagation delay	$33 + 0.55 \times C_L$	5 V	-	60	120	ns
		$14 + 0.23 \times C_L$	10 V	-	25	50	ns
		$12 + 0.16 \times C_L$	15 V	-	20	40	ns
t <sub>PLH</sub>	LOW to HIGH propagation delay	$23 + 0.55 \times C_L$	5 V	-	50	100	ns
		$14 + 0.23 \times C_L$	10 V	-	25	45	ns
		$12 + 0.16 \times C_L$	15 V	-	20	35	ns
t <sub>THL</sub>	HIGH to LOW output transition time	$10 + 1.00 \times C_L$	5 V	-	60	120	ns
		$9 + 0.42 \times C_L$	10 V	-	30	60	ns
		$6 + 0.28 \times C_L$	15 V	-	20	40	ns
t <sub>TLH</sub>	LOW to HIGH output transition time	$10 + 1.00 \times C_L$	5 V	-	60	120	ns
		$9 + 0.42 \times C_L$	10 V	-	30	60	ns
		$6 + 0.28 \times C_L$	15 V	-	20	40	ns

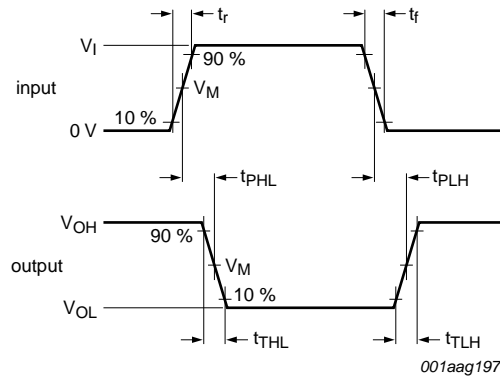
[1] The typical value of the propagation delay and output transition time can be calculated with the extrapolation formula ( $C_L$  in pF).

**Table 8. Dynamic power dissipation**

$V_{SS} = 0\text{ V}$ ;  $t_r = t_f \leq 20\text{ ns}$ ;  $T_{amb} = 25\text{ }^{\circ}\text{C}$ .

Symbol	Parameter	V <sub>DD</sub>	Typical formula	Where
P <sub>D</sub>	dynamic power dissipation	5 V	$P_D = 1100 \times f_i + \Sigma(f_o \times C_L) \times V_{DD}^2$ (μW)	$f_i$ = input frequency in MHz;
		10 V	$P_D = 5000 \times f_i + \Sigma(f_o \times C_L) \times V_{DD}^2$ (μW)	$f_o$ = output frequency in MHz;
		15 V	$P_D = 14200 \times f_i + \Sigma(f_o \times C_L) \times V_{DD}^2$ (μW)	$C_L$ = output load capacitance in pF; $\Sigma(f_o \times C_L)$ = sum of the outputs; $V_{DD}$ = supply voltage in V.

11. Waveforms

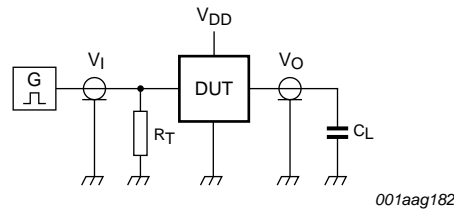


Measurement points are given in [Table 9](#).  
 Logic levels:  $V_{OL}$  and  $V_{OH}$  are typical output voltage levels that occur with the output load.

**Fig 4. Propagation delay, output transition time**

**Table 9. Measurement points**

Supply voltage	Input	Output
$V_{DD}$	$V_M$	$V_M$
5 V to 15 V	$0.5V_{DD}$	$0.5V_{DD}$



Test data is given in [Table 10](#).  
 Definitions for test circuit:  
 DUT = Device Under Test.  
 $C_L$  = load capacitance including jig and probe capacitance.  
 $R_T$  = termination resistance should be equal to the output impedance  $Z_o$  of the pulse generator.

**Fig 5. Test circuit for measuring switching times**

**Table 10. Test data**

Supply voltage	Input	Load
$V_{DD}$	$V_I$	$C_L$
5 V to 15 V	$V_{SS}$ or $V_{DD}$	$\leq 20$ ns
		50 pF

12. Package outline

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1

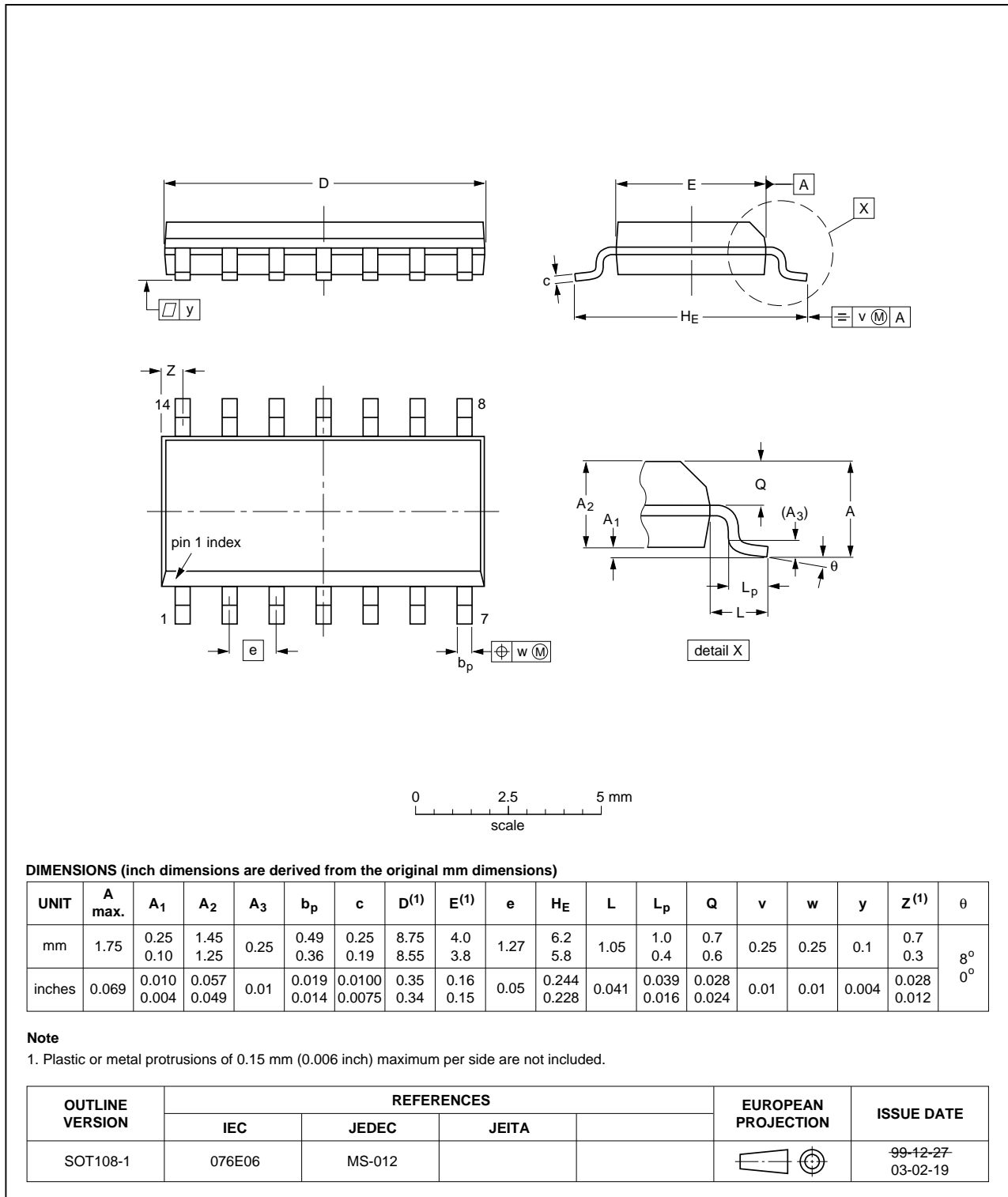


Fig 6. Package outline SOT108-1 (SO14)

## 13. Abbreviations

Table 11. Abbreviations

Acronym	Description
HBM	Human Body Model
ESD	ElectroStatic Discharge
MM	Machine Model
MIL	Military

## 14. Revision history

Table 12. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
HEF4001B_Q100 v.1	20130220	Product data sheet	-	-



## 15. Legal information

### 15.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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